

RELIABILITY REPORT FOR
MAX8865SEUA+T / MAX8865TEUA+T
PLASTIC ENCAPSULATED DEVICES

June 16, 2016

MAXIM INTEGRATED

160 RIO ROBLES
SAN JOSE, CA 95134

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| Approved by |
| Eric Wright |
| Quality Assurance |
| Reliability Engineer |

Conclusion

The MAX8865SEUA+T / MAX8865TEUA+T successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX8865 and MAX8866 dual, low-dropout linear regulators operate from a +2.5V to +5.5V input range and deliver up to 100mA. At 200mA total load, the PMOS pass transistors keep the supply current at 145 μ A, making these devices ideal for battery-operated portable equipment such as cellular phones, cordless phones, and modems. The devices feature Dual Mode(tm) operation: their output voltages are preset (at 3.15V for the "T" versions, 2.84V for the "S" versions, or 2.80V for the "R" versions) or can be adjusted with external resistor dividers. Other features include independent low-power shutdown, short-circuit protection, thermal shutdown protection, and reverse battery protection. The MAX8866 also includes an auto-discharge function, which actively discharges the selected output voltage to ground when the device is placed in shutdown mode. Both devices come in a miniature 8-pin μ MAX® package.

II. Manufacturing Information

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|--------------------------------|--|
| A. Description/Function: | Dual, Low-Dropout, 100mA Linear Regulators |
| B. Process: | S12 |
| C. Fabrication Location: | USA |
| D. Assembly Location: | Philippines, Thailand |
| E. Date of Initial Production: | Pre-1997 |

III. Packaging Information

| | |
|--|--------------------------|
| A. Package Type: | 8-pin uMAX |
| B. Lead Frame: | Copper |
| C. Lead Finish: | 100% matte Tin |
| D. Die Attach: | Conductive |
| E. Bondwire: | Au (1.3 mil dia.) |
| F. Mold Material: | Epoxy with silica filler |
| G. Assembly Diagram: | #05-1701-0284 |
| H. Flammability Rating: | Class UL94-V0 |
| I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C | Level 1 |
| J. Single Layer Theta Ja: | 221°C/W |
| K. Single Layer Theta Jc: | 41.9°C/W |
| L. Multi Layer Theta Ja: | 206.3°C/W |
| M. Multi Layer Theta Jc: | 41.9°C/W |

IV. Die Information

| | |
|----------------------------|---|
| A. Dimensions: | 70X56 mils |
| B. Passivation: | Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide) |
| C. Interconnect: | Al/0.5%Cu with Ti/TiN Barrier |
| D. Backside Metallization: | None |
| E. Minimum Metal Width: | 1.2 microns (as drawn) |
| F. Minimum Metal Spacing: | 1.2 microns (as drawn) |
| G. Bondpad Dimensions: | |
| H. Isolation Dielectric: | SiO ₂ |
| I. Die Separation Method: | Wafer Saw |

V. Quality Assurance Information

- A. Quality Assurance Contacts: Eric Wright (Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% for all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 80 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 13.7 \times 10^{-9}$$

$$\lambda = 13.7 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the S12 Process results in a FIT Rate of 0.17 @ 25C and 3.00 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing

The PW87 die type has been found to have all pins able to withstand an HBM transient pulse of +/-1000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-100mA and overvoltage per JEDEC JESD78.

Table 1
Reliability Evaluation Test Results
MAX8865SEUA+T / MAX8865TEUA+T

| TEST ITEM | TEST CONDITION | FAILURE IDENTIFICATION | SAMPLE SIZE | NUMBER OF FAILURES | COMMENTS |
|----------------------------------|--|----------------------------------|-------------|--------------------|----------|
| Static Life Test (Note 1) | Ta = 135C Biased Time = 192 hrs. | DC Parameters & functionality | 80 | 0 | |

Note 1: Life Test Data may represent plastic DIP qualification lots.